

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

Pin	Function
D0*, D1*, D0 **, D1 **	ECL Data Inputs
Q, Q	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. TRUTH TABLE

D0	D1	D0	D1	Q	Q
L H H	L H L H	ΗΗΙL	HLHL	LLT	ннпг

Table 3. ATTRIBUTES

Charac	eteristics	Value					
Internal Input Pulldown Resist	or	75 kΩ					
Internal Input Pullup Resistor	37.5	kΩ					
ESD Protection	> 4 kV > 200 V > 2 kV						
Moisture Sensitivity, Indefinite	Time Out of Drypack (Note 1)	Pb Pkg	Pb-Free Pkg				
	SOIC-8 TSSOP-8 DFN8	Level 1 Level 1 Level 1	Level 1 Level 3 Level 1				
Flammability Rating	UL 94 V-0	@ 0.125 in					
Transistor Count		137 D	evices				
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test							

^{1.} For additional information, see Application Note AND8003/D.

 $^{^{\}star}$ Pins will default LOW when left open. ** Pins will default to VCC/2when left open.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$V_{I} \leq V_{CC}$ $V_{I} \geq V_{EE}$	6 -6	V V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W °C/W
θЈС	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44	°C/W
θЈА	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
θЈС	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
θЈА	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
θJC	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. 10EP DC CHARACTERISTICS, PECL $V_{CC} = 3.3 \text{ V}$, $V_{EE} = 0 \text{ V}$ (Note 3)

			-40°C			25°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	20	24	29	20	24	29	20	24	29	mA
V _{OH}	Output HIGH Voltage (Note 4)	2165	2290	2415	2230	2355	2480	2290	2415	2540	mV
V _{OL}	Output LOW Voltage (Note 4)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2090		2415	2155		2480	2215		2540	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1365		1690	1460		1755	1490		1815	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	2.0		3.3	2.0		3.3	2.0		3.3	V
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current E				0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 3. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.3 V to -2.2 V.
- 4. All loading with 50 Ω to V_{CC} 2.0 V.
- V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

^{2.} JEDEC standard multilayer board - 2S2P (2 signal, 2 power)

Table 6. 10EP DC CHARACTERISTICS, PECL V_{CC} = 5.0 V, V_{EE} = 0 V (Note 6)

				-40°C			25°C					
Symbol	Characteristic	Ī	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		20	24	29	20	24	29	20	24	29	mA
V _{OH}	Output HIGH Voltage (Note 7)		3865	3990	4115	3930	4055	4180	3990	4115	4240	mV
V _{OL}	Output LOW Voltage (Note 7)		3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
V _{IH}	Input HIGH Voltage (Single-Ended)		3790		4115	3855		4180	3915		4240	mV
V _{IL}	Input LOW Voltage (Single-Ended)		3065		3390	3130		3455	3190		3515	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 8)		2.0		5.0	2.0		5.0	2.0		5.0	V
I _{IH}	Input HIGH Current				150			150			150	μΑ
I _{IL}	•	D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 6. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +2.0 V to -0.5 V.
- 7. All loading with 50 Ω to V_{CC} 2.0 V.
- V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 7. 10EP DC CHARACTERISTICS, NECL $V_{CC} = 0 \text{ V}$, $V_{EE} = -5.5 \text{ V}$ to -3.0 V (Note 9)

			-40°C			25°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	20	24	29	20	24	29	20	24	29	mA
V _{OH}	Output HIGH Voltage (Note 10)	-1135	-1010	-885	-1070	-945	-820	-1010	-885	-760	mV
V _{OL}	Output LOW Voltage (Note 10)	-1935	-1810	-1685	-1870	-1745	-1620	-1810	-1685	-1560	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1210		-885	-1145		-820	-1085		-760	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1935		-1610	-1870		-1545	-1810		-1485	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 11)	V _{EE}	+2.0	0.0	V _{EE}	+2.0	0.0	V _{EE}	+2.0	0.0	V
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current DDD	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

^{9.} Input and output parameters vary 1:1 with $V_{\mbox{\footnotesize CC}}$.

^{10.} All loading with 50 Ω to V_{CC} – 2.0 V.

^{11.} V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 8. 100EP DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 12)

			-40°C			25°C						
Symbol	Characteristic	N	/lin	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	1	15	25	32	17	27	36	19	28	38	mA
V _{OH}	Output HIGH Voltage (Note 13)	21	155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V _{OL}	Output LOW Voltage (Note 13)	13	355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	20	075		2420	2075		2420	2075		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	13	355		1675	1355		1675	1355		1675	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 14)	2	2.0		3.3	2.0		3.3	2.0		3.3	V
I _{IH}	Input HIGH Current				150			150			150	μΑ
I _{IL}		_).5 150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 9. 100EP DC CHARACTERISTICS, PECL $V_{CC} = 5.0 \text{ V}$, $V_{EE} = 0 \text{ V}$ (Note 15)

			-40°C				25°C			85°C		
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		15	25	32	17	27	36	19	28	38	mA
V _{OH}	Output HIGH Voltage (Note 16)	7	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
V _{OL}	Output LOW Voltage (Note 16)	7	3055	3180	3305	3055	3180	3305	3055	3180	3305	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	7	3775		4120	3775		4120	3775		4120	mV
V _{IL}	Input LOW Voltage (Single-Ended)	7	3055		3375	3055		3375	3055		3375	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 17)		2.0		5.0	2.0		5.0	2.0		5.0	V
I _{IH}	Input HIGH Current				150			150			150	μΑ
I _{IL}		D -	0.5 –150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

^{12.} Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to -2.2 V.

^{13.} All loading with 50 Ω to V_{CC} – 2.0 V.

^{14.} V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential

^{15.} Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +2.0 V to -0.5 V. 16. All loading with 50 Ω to V_{CC} - 2.0 V. 17. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 10. 100EP DC CHARACTERISTICS, NECL $V_{CC} = 0 \text{ V}$, $V_{EE} = -5.5 \text{ V}$ to -3.0 V (Note 18)

		-40°C				25°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	15	25	32	17	27	36	19	28	38	mA
V _{OH}	Output HIGH Voltage (Note 19)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V _{OL}	Output LOW Voltage (Note 19)	-1945	-1820	-1695	-1945	-1820	-1695	-1945	-1820	-1695	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1945		-1625	-1945		-1625	-1945		-1625	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 20)	V _{EE} -	+2.0	0.0	V _{EE}	+2.0	0.0	V _{EE}	+2.0	0.0	V
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 11. AC CHARACTERISTICS $V_{CC} = 0 \text{ V}$; $V_{EE} = -3.0 \text{ V}$ to -5.5 V or $V_{CC} = 3.0 \text{ V}$ to 5.5 V; $V_{EE} = 0 \text{ V}$ (Note 21)

		-40°C			25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Frequency (Figure 2)		> 3			> 3			> 3		GHz
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential	160	210	260	170	220	270	210	260	320	ps
t _{UITTER}	Random Clock Jitter (Figure 2)		0.2	< 1		0.2	< 1		0.2	1.5	ps
V _{PP}	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV
t _r t _f	Output Rise/Fall Times Q (20% – 80%)	70	120	170	80	130	180	100	150	200	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

21. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC} – 2.0 V.

^{18.} Input and output parameters vary 1:1 with V_{CC}.

^{19.} All loading with 50 Ω to V_{CC} – 2.0 V.

^{20.} V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

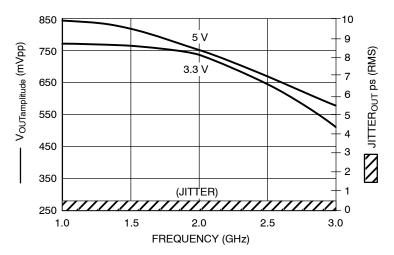


Figure 2. $F_{max}/Jitter @ 25^{\circ}C$

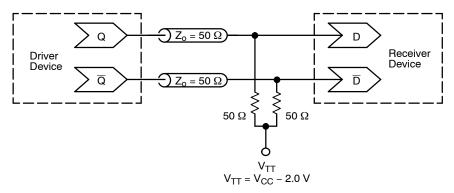


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]				
MC10EP05D	SOIC-8	98 Units / Rail				
MC10EP05DG	SOIC-8 (Pb-Free)	98 Units / Rail				
MC10EP05DR2	SOIC-8	2500 / Tape & Reel				
MC10EP05DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel				
MC10EP05DT	TSSOP-8	100 Units / Rail				
MC10EP05DTG	TSSOP-8 (Pb-Free)	100 Units / Rail				
MC10EP05DTR2	TSSOP-8	2500 / Tape & Reel				
MC10EP05DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel				
MC10EP05MNR4	DFN8	1000 / Tape & Reel				
MC10EP05MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel				
MC100EP05D	SOIC-8	98 Units / Rail				
MC100EP05DG	SOIC-8 (Pb-Free)	98 Units / Rail				
MC100EP05DR2	SOIC-8	2500 / Tape & Reel				
MC100EP05DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel				
MC100EP05DT	TSSOP-8	100 Units / Rail				
MC100EP05DTG	TSSOP-8 (Pb-Free)	100 Units / Rail				
MC100EP05DTR2	TSSOP-8	2500 / Tape & Reel				
MC100EP05DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel				
MC100EP05MNR4	DFN8	1000 / Tape & Reel				
MC100EP05MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel				

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AND8001/D - The ECL Translator Guide
AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

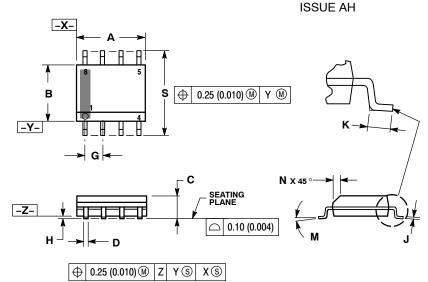
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

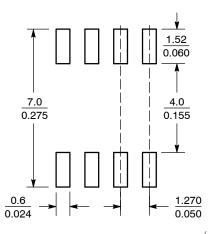
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
 PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW
 ETAINARD 18 751-07
- STANDARD IS 751-07.

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
O	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
7	0.19	0.25	0.007	0.010
Κ	0.40	1.27	0.016	0.050
М	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

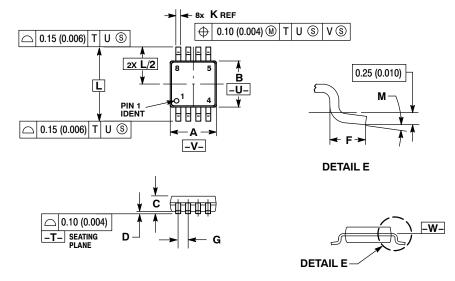


 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH
 OR GATE BURRS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED 0.25 (0.010)
 PER SIDE.

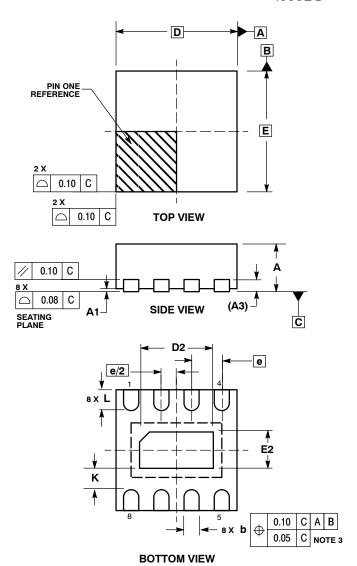
 5. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.

 6. DIMENSION A AND B ARE TO BE DETERMINED
 AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6 °	0°	6°

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D



NOTES:

- DIMENSIONING AND TOLERANCING
 PER ASME Y14.5M, 1994 .
- CONTROLLING DIMENSION: MILLIMETERS.
- MILLIMETERS.

 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
- 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.80	1.00		
A1	0.00	0.05		
A3	0.20 REF			
b	0.20	0.30		
D	2.00 BSC			
D2	1.10	1.30		
E	2.00 BSC			
E2	0.70	0.90		
е	0.50 BSC			
K	0.20			
L	0.25	0.35		

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